

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7848564

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the THE ASSIGNEE'S NAME previously recorded on Reel 054384 Frame 0464. Assignor(s) hereby confirms the ASSIGNMENT.
RESUBMIT DOCUMENT ID:	507752645
CONVEYING PARTY DATA	
Name	Execution Date
ENG KWONG LEE	08/27/2020
CHEW CHING LIM	08/27/2020
RECEIVING PARTY DATA	
Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BLVD
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17088666
CORRESPONDENCE DATA	
Fax Number:	(617)849-5451
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	patint@vjp.de
Correspondent Name:	VIERING, JENTSCHURA & PARTNER MBB
Address Line 1:	C/O 444 BRICKELL AVENUE
Address Line 2:	SUITE 700
Address Line 4:	MIAMI, FLORIDA 33131
ATTORNEY DOCKET NUMBER:	P118812US
NAME OF SUBMITTER:	BENJAMIN L. VON RUEDEN
SIGNATURE:	/Benjamin L. von Rueden, Reg.# 74,693/
DATE SIGNED:	03/16/2023
Total Attachments: 5	
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Assignment Recordation Service Division
Director of the United States Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

CORRECTION OF AN ASSIGNMENT RECORD COVER SHEET

Dear Sir or Madam:

This letter is respectfully submitted correct the Assignee's name previously recorded on Reel 054384 Frame 0464 in accordance with 37 CFR 3.34 and MPEP § 323.01. The Cover Sheet was erroneously submitted with the incorrect assignee's name. The correct assignee is **INTEL CORPORATION**. Accordingly, Applicant respectfully requests the Cover Sheet be corrected to reflect the proper assignee's name, which is reflected in the uploaded assignment document.

The Commissioner is authorized to charge any additional fees required by this paper or credit any overpayment to Deposit Account Number 50-4666.

Dated: March 16, 2023

Respectfully Submitted,

By /Benjamin L. von Rueden/
Benjamin L. von Rueden
Reg. No: 74,693

Viering, Jentschura & Partner mbB
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Miami, FL 33131
Phone: (617) 275-2642
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vjp-us@vjp.de

Attorney for Applicants

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6404378

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	ENG KWONG LEE	08/27/2020
	CHEW CHING LIM	08/27/2020
RECEIVING PARTY DATA		
Name:	INTEL IP CORPORATION <u>INTEL CORPORATION</u>	
Street Address:	2200 MISSION COLLEGE BLVD	
City:	SANTA CLARA	
State/Country:	CALIFORNIA	
Postal Code:	95054	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	17088666
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Correspondent Name:	VIERING, JENTSCHURA & PARTNER MBB	
Address Line 1:	444 BRICKELL AVENUE	
Address Line 2:	SUITE 700	
Address Line 4:	MIAMI, FLORIDA 33131	
ATTORNEY DOCKET NUMBER:	P118812US	
NAME OF SUBMITTER:	BENJEMAN L. VON RUEDEN	
SIGNATURE:	/Benjeman L. von Rueden, Reg.# 74,693/	
DATE SIGNED:	11/17/2020	
Total Attachments: 2		
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ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

Lee, Eng Kwong; Lim, Chew Ching

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

STIFFENER FOR DIE CRACK PREVENTION IN SEMICONDUCTOR PACKAGES

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on November 4, 2020 as
US Application Number 17/088,666 and
COUNTRY or International Office

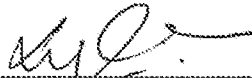
which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history

thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and


covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



Lee, Eng Kwong

8/27/2020

Date signed



Lim, Chew Ching

8/27/2020

Date signed